

## Device Specification (Preliminary)

### ELECTRICAL CHARACTERISTICS

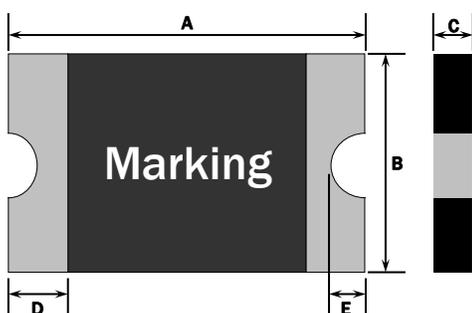
Part Number	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max</sub> (Vdc)	I <sub>max</sub> (A)	P <sub>d max</sub> (W)	Maximum Time-to-Trip		Resistance	
						Current (A)	Time (Sec.)	R <sub>min</sub> (Ω)	R <sub>lmax</sub> (Ω)
1206L500SL	5.00	10.00	6	50	1.00	25.0	2.00	0.001	0.012

- Note:
- I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 20°C still air.
  - I<sub>trip</sub> = Trip Current: minimum current at which the device will trip in 20°C still air.
  - V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>)
  - I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>)
  - P<sub>d</sub> = Power dissipated from device when in the tripped state at 20°C still air.
  - R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.
  - R<sub>lmax</sub> = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

**Caution** : Operation beyond the specified rating may result in damage and possible arcing and flame.

Figure

Solder Pad Layout (mm)



### PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	min	Max.	Min.	Max.
1206L600SL	3.00	3.40	1.50	1.80	0.60	1.00	0.25	0.75	0.05	0.45

**THERMAL DERATING CHART –  $I_{hold}/I_{trip}$  (Amps)**

**Recommended Data**

Part Number		Ambient Operation Temperature								
		-40 °C	-20 °C	0 °C	23 °C	40 °C	50 °C	60 °C	70 °C	85 °C
1206L500SL	$I_{hold}$	7.20	6.60	5.80	5.00	4.25	3.80	3.40	3.00	2.10
	$I_{trip}$	14.40	13.20	11.60	10.00	8.50	7.60	6.80	6.00	4.20